



General Description

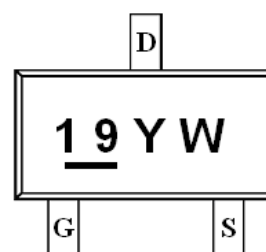
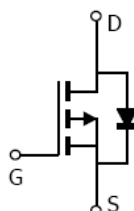
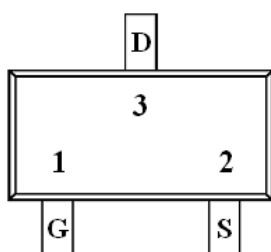
AFP2319AS, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

Features

- -40V/-3.0A, $R_{DS(ON)}=90m\Omega@V_{GS}=-10V$
- -40V/-2.4A, $R_{DS(ON)}=120m\Omega@V_{GS}=-4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-23 package design

Pin Description (SOT-23)



Application

- Load Switch
- DC-DC System

Pin Define

Pin	Symbol	Description
1	G	Gate
2	S	Source
3	D	Drain

Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFP2319ASS23RG	<u>19</u> YW	SOT-23	Tape & Reel	3000 EA

- ※ 19 parts code
- ※ Y year code (0 ~ 9)
- ※ W week code (A ~ Z = 1 ~ 26 / a ~ z = 27 ~ 52)
- ※ AFP2319ASS23RG : 7" Tape & Reel ; Pb- Free ; Halogen- Free



Absolute Maximum Ratings

(T_A=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V _{DSS}	-40	V
Gate –Source Voltage	V _{GSS}	±20	V
Continuous Drain Current(T _J =150°C)	I _D	T _A =25°C	-3.5
		T _A =70°C	-2.4
Pulsed Drain Current	I _{DM}	-12	A
Continuous Source Current(Diode Conduction)	I _S	-1.0	A
Power Dissipation	P _D	T _A =25°C	1.25
		T _A =70°C	0.8
Operating Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	-55/150	°C
Thermal Resistance-Junction to Ambient	R _{θJA}	120	°C/W

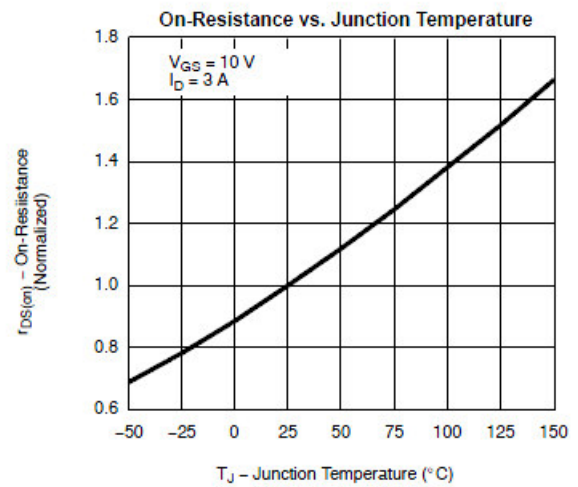
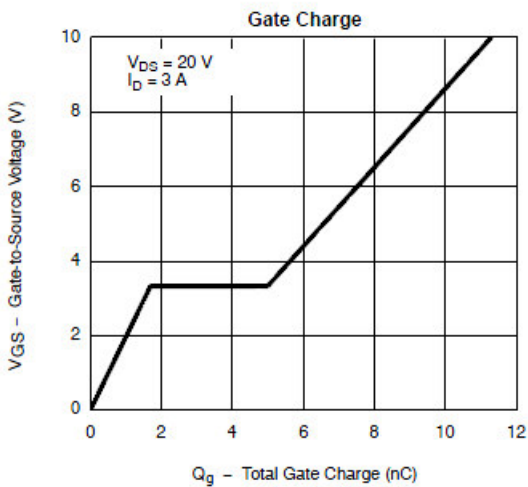
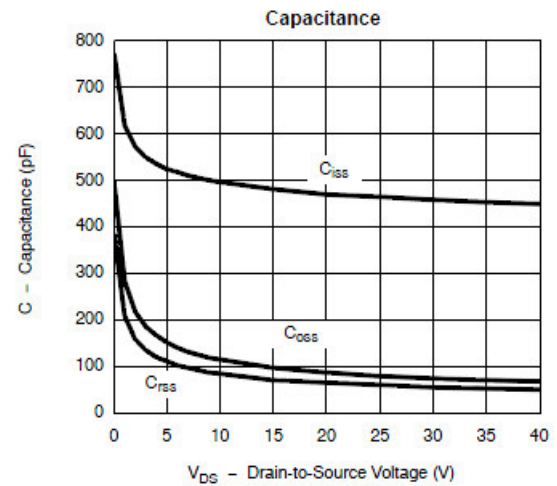
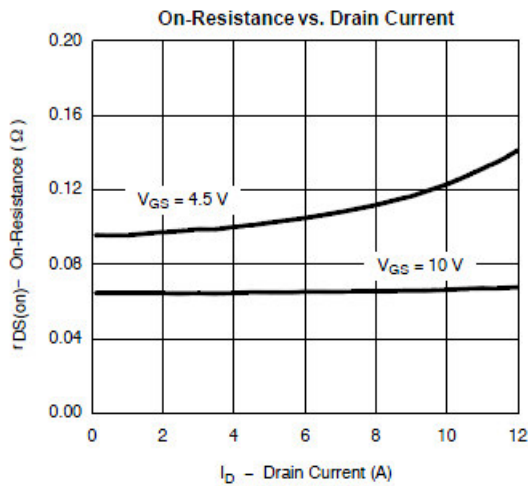
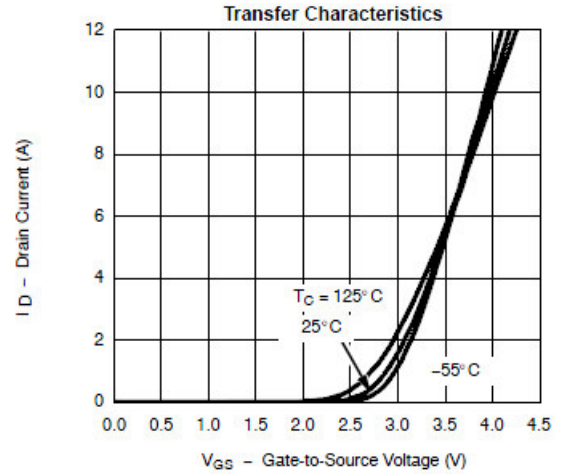
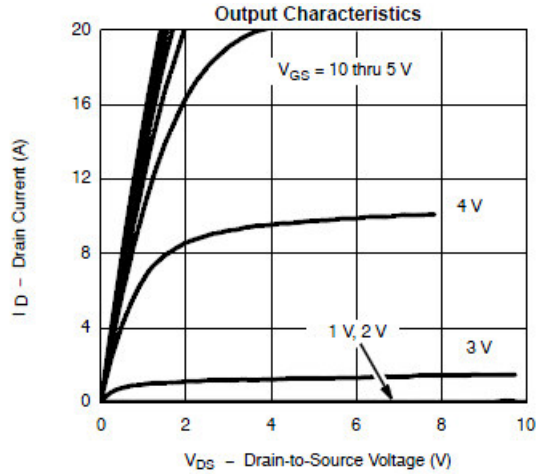
Electrical Characteristics

(T_A=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250uA	-40			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250uA	-1.0		-2.0	V
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±12V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-32V, V _{GS} =0V			-1	uA
		V _{DS} =-32V, V _{GS} =0V T _J =85°C			-30	
On-State Drain Current	I _{D(on)}	V _{DS} ≤ -5V, V _{GS} =-10V	-6			A
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =-10V, I _D =-3.0A		75	90	mΩ
		V _{GS} =-4.5V, I _D =-2.4A		90	120	
Forward Transconductance	g _{FS}	V _{DS} =-5V, I _D =-3.0A		8		S
Diode Forward Voltage	V _{SD}	I _S =-1.25A, V _{GS} =0V		-0.75	-1.3	V
Dynamic						
Total Gate Charge	Q _g	V _{DS} =-20V, V _{GS} =-10V I _D ≡-3.0A		10	15	nC
Gate-Source Charge	Q _{gs}			2.0		
Gate-Drain Charge	Q _{gd}			3.0		
Input Capacitance	C _{iss}	V _{DS} =-20V, V _{GS} =0V f=1MHz		480		pF
Output Capacitance	C _{oss}			90		
Reverse Transfer Capacitance	C _{rss}			70		
Turn-On Time	t _{d(on)}	V _{DD} =-20V, R _L =20Ω I _D ≡-1.0A, V _{GEN} =-4.5V R _G =6.0Ω		8	15	ns
	t _r			15	25	
Turn-Off Time	t _{d(off)}			25	40	
	t _f			25	40	

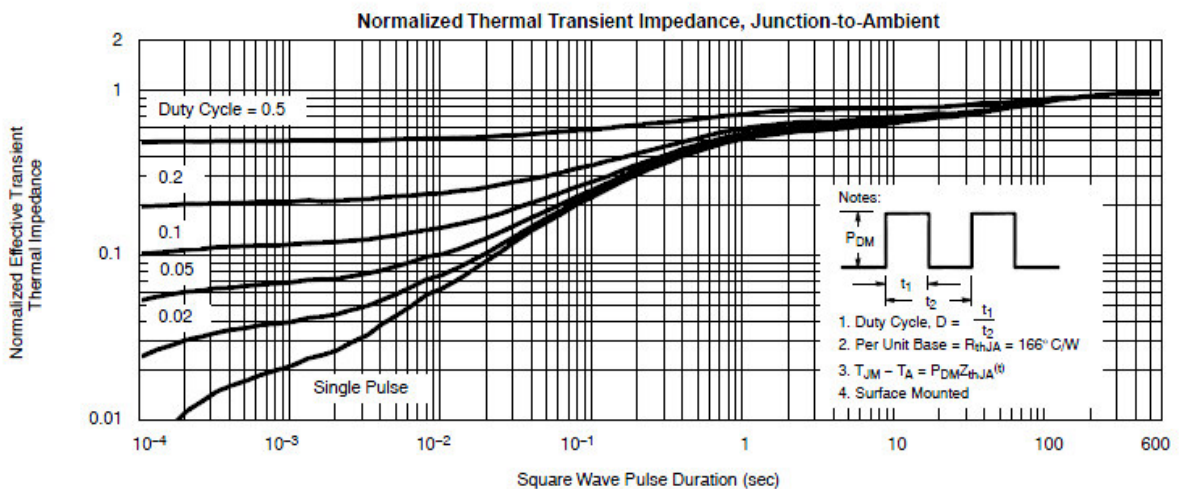
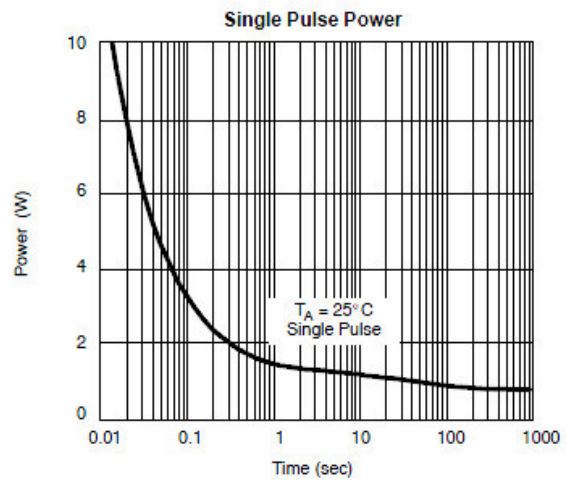
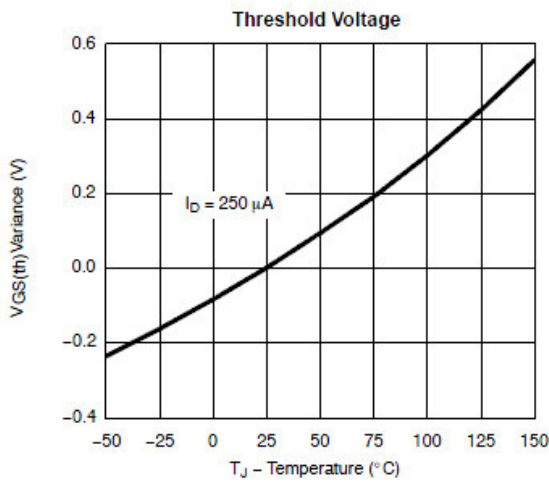
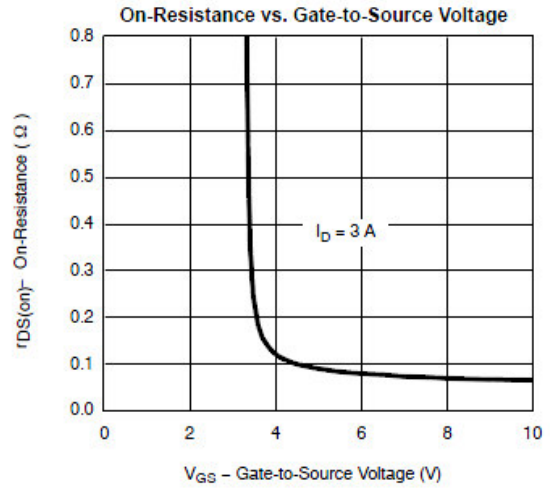
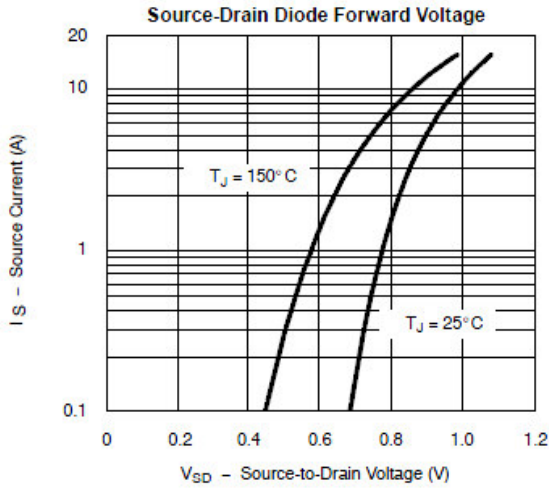


Typical Characteristics





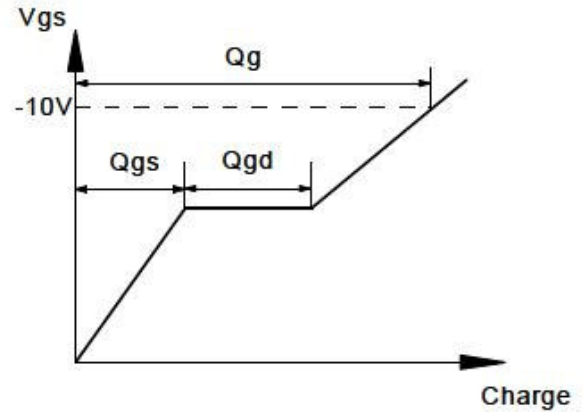
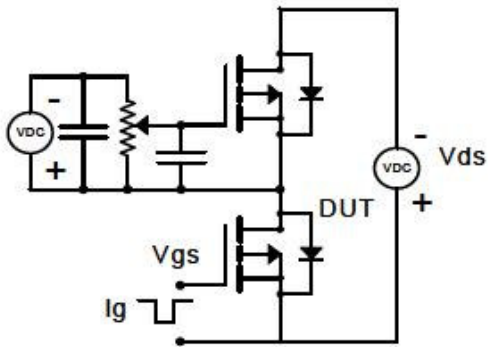
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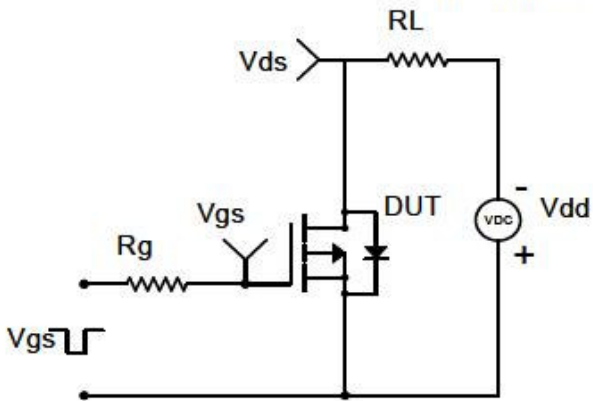


Typical Characteristics

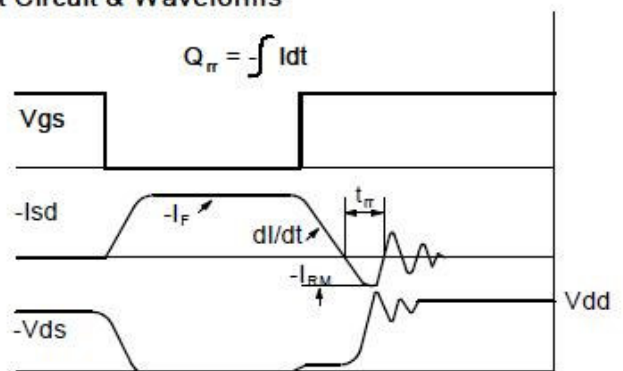
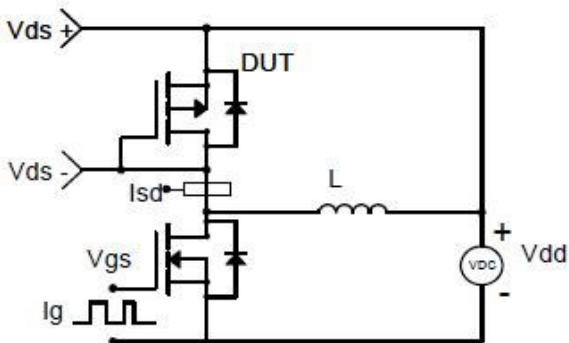
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

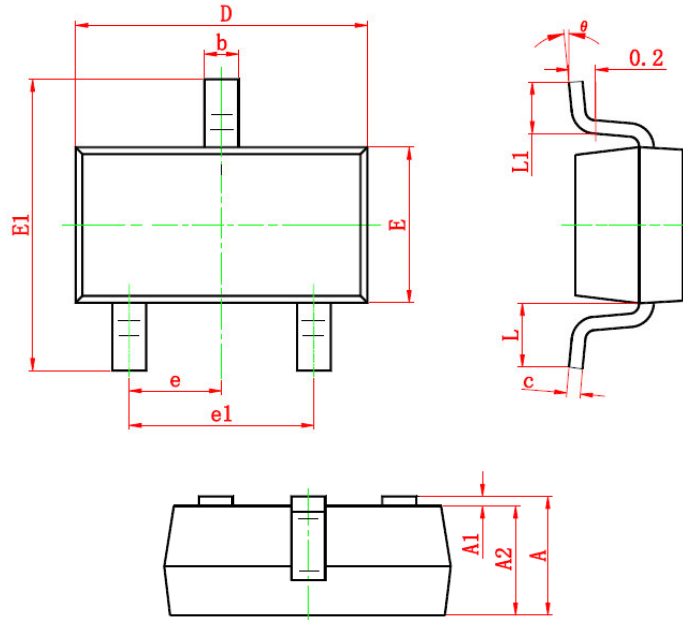


Diode Recovery Test Circuit & Waveforms





Package Information (SOT-23)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.200	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.100	0.035	0.039
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	6°

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